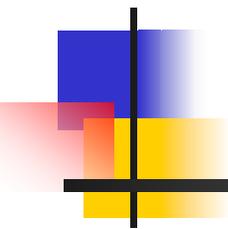
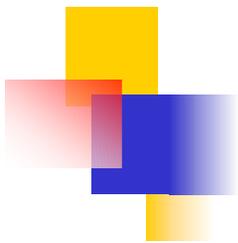


Security Evaluation Against Electromagnetic Analysis at Design Time



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University of Cambridge



Outline

- Motivation
- Simulation methodology for EMA
 - System partitioning
 - Simulation flow
 - Types of EM emissions
 - EMA measurement equipment
- Results
- Conclusion

Motivation – side channel attacks

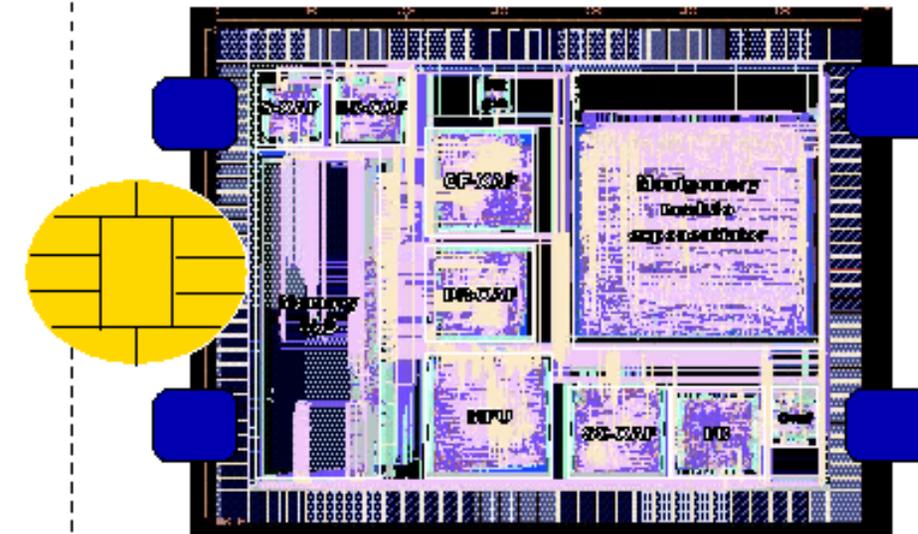
ISO Interface Chip Surface

1

←
**Timing of
computation**

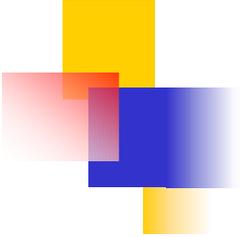
2

←
**Power
consumption**



**Electromagnetic
radiation**

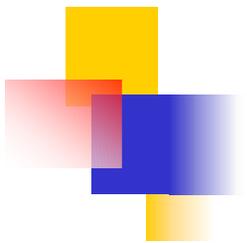
3
↓



Motivation

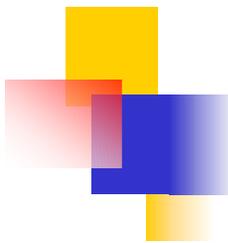
Post-manufacture test:

- Time consuming
- Error prone
- Expensive
- So that has driven the study of design-time security evaluation



EM Simulator

- EM Simulation -- Solve Maxwell's Equations for simulating wave propagation
 - Pro: accurate
 - Con: computationally complex, time-consuming



EMA measurement equipment

- Near-field ($r < \lambda/2\pi$) electric field sensors

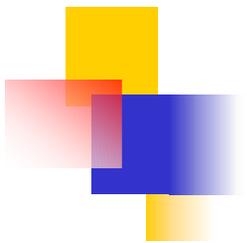
$$E \propto I$$

- Near-field magnetic field sensors

$$B \propto I$$

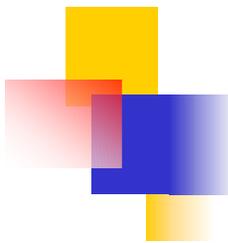
- Far-field ($r > \lambda/2\pi$) electromagnetic field sensors

$$emf \propto I$$

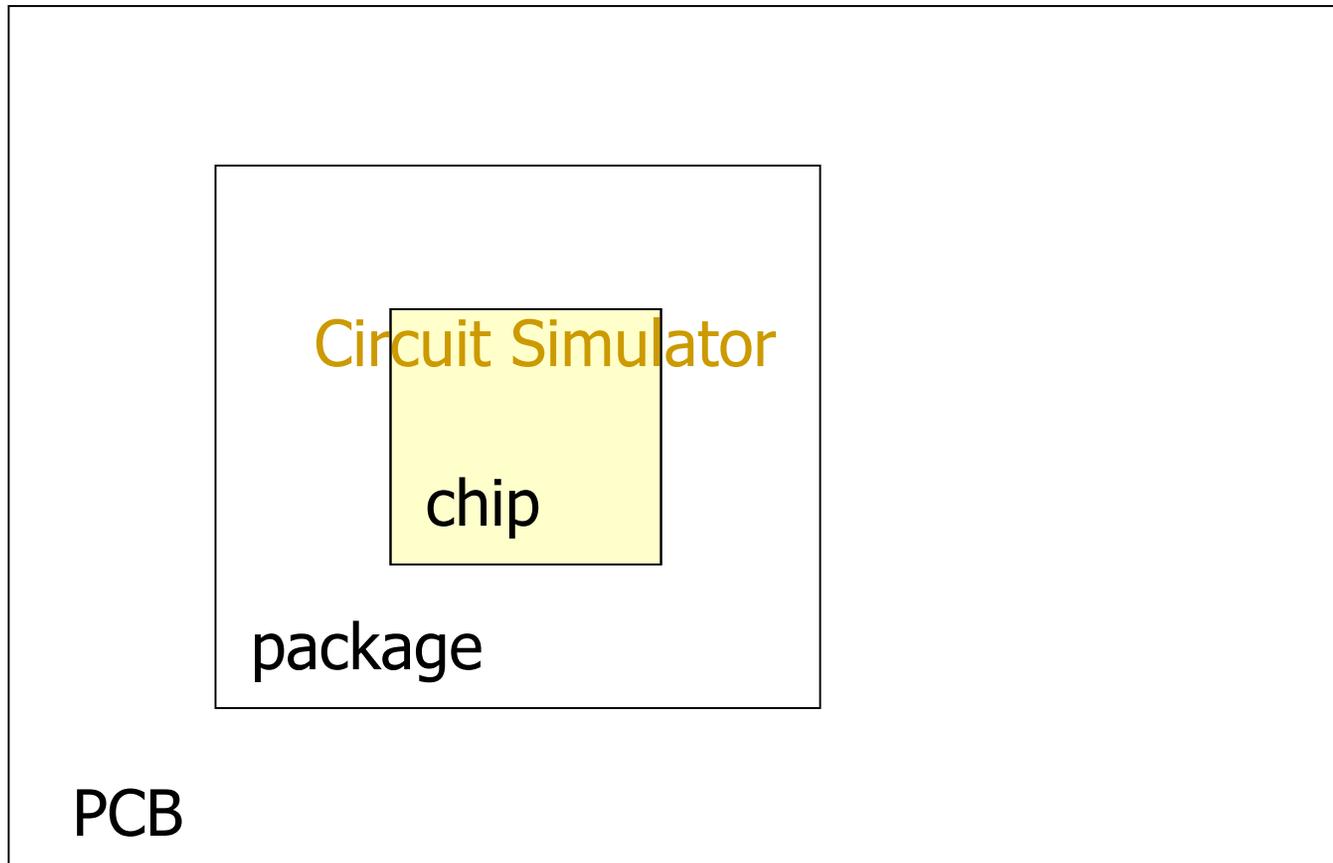


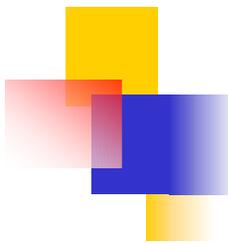
Circuit Simulator

- Circuit Simulation – solve for V & I according to Kirchhoff's voltage and current laws
 - Pro: fast
 - Con: accuracy limited by the accuracy of lumped element models; validity limited by range of frequencies, geometries etc

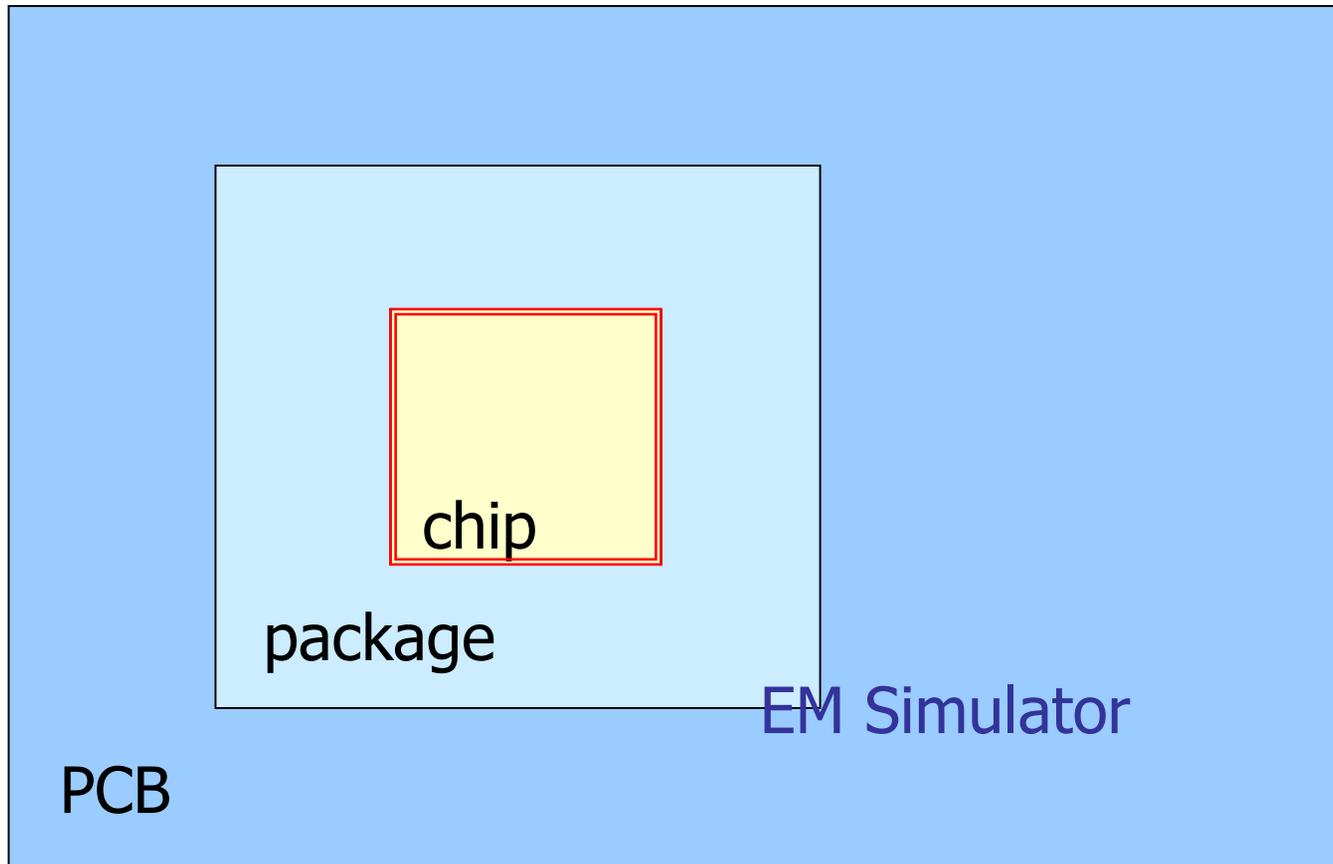


System partitioning

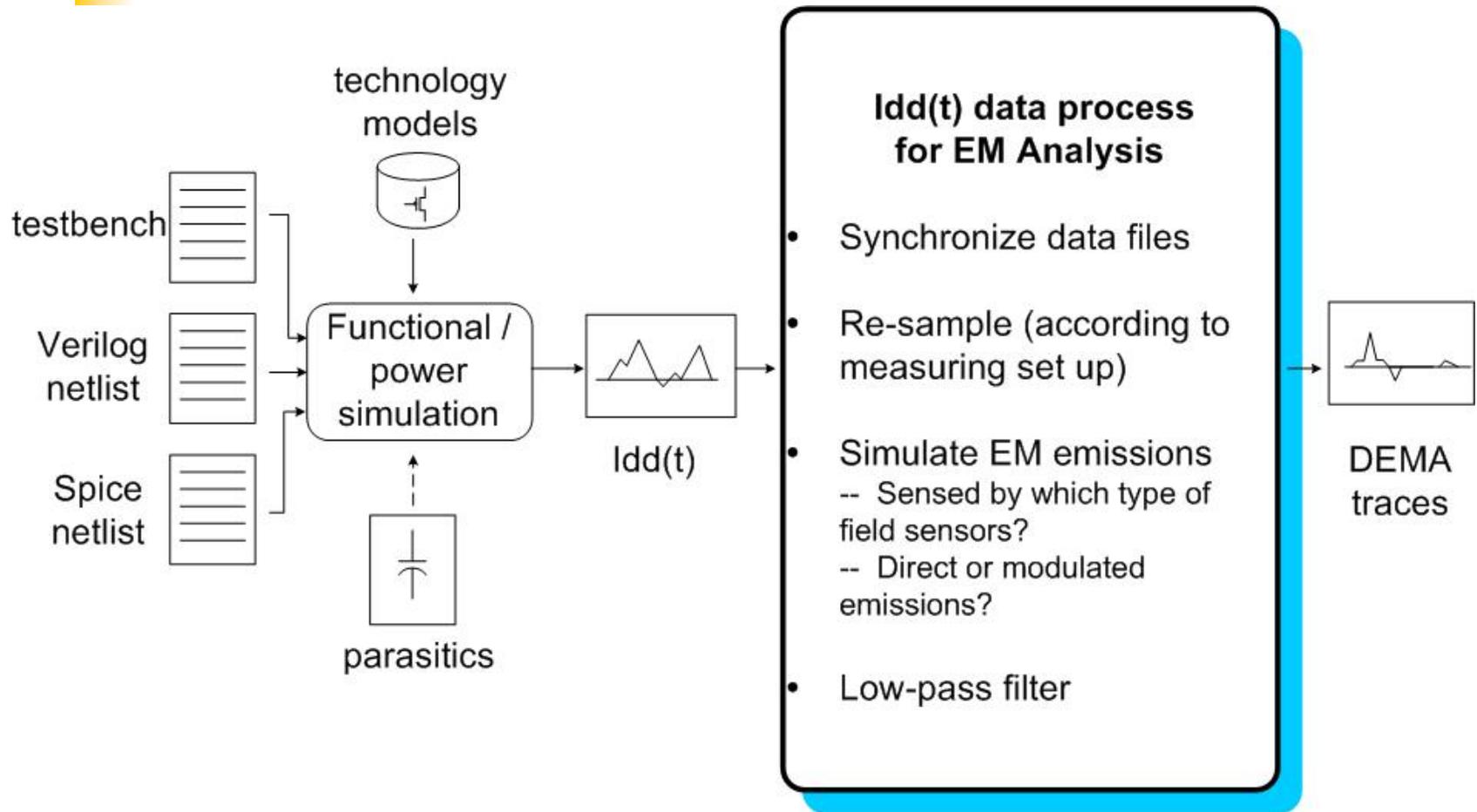


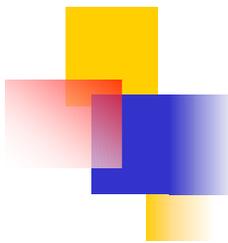


System partitioning



EM analysis simulation procedure





EMA measurement equipment

- Near-field ($r < \lambda/2\pi$) electric field sensors

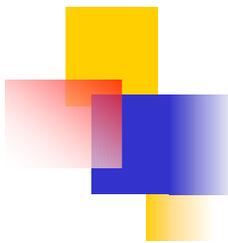
$$E \propto I$$

- Near-field magnetic field sensors

$$B \propto I \qquad V \propto \frac{dB}{dt} \propto \frac{dI}{dt}$$

- Far-field ($r > \lambda/2\pi$) electromagnetic field sensors

$$emf \propto I$$

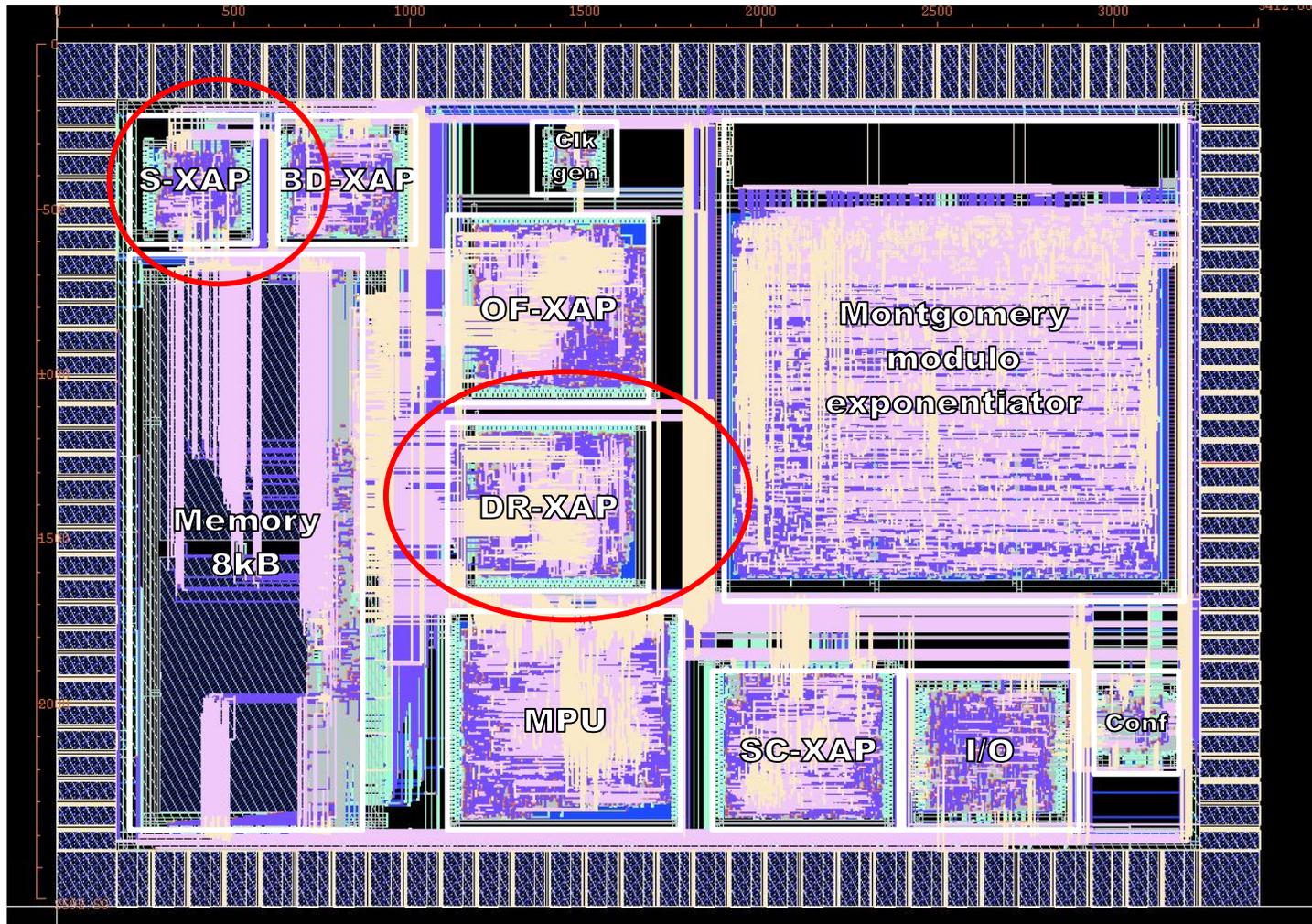


Types of EM emissions

- Direct Emissions
- Modulated Emissions
 - Amplitude Modulation
 - Angle Modulation (phase or frequency)

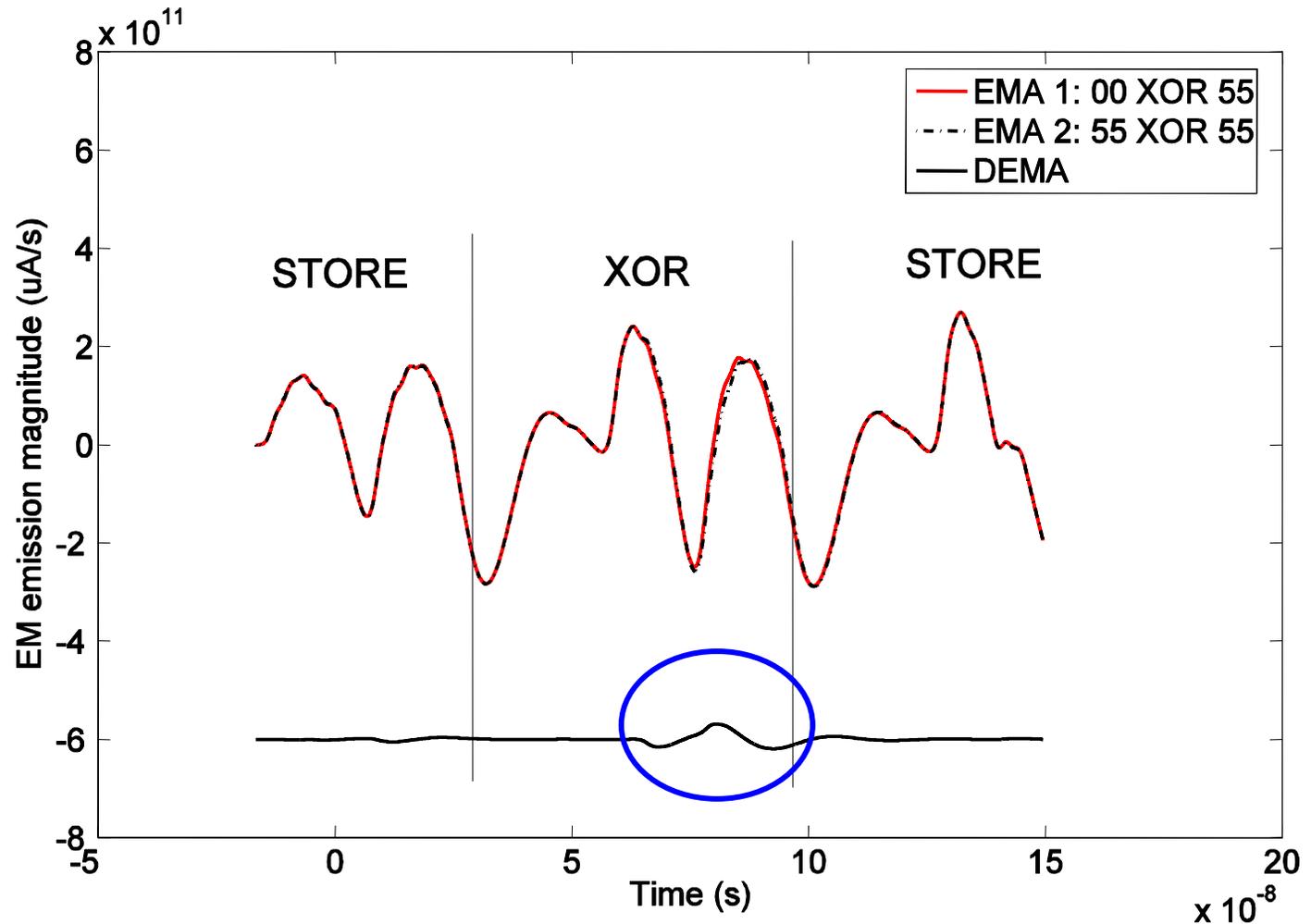
Simulation setup

- Springbank test chip



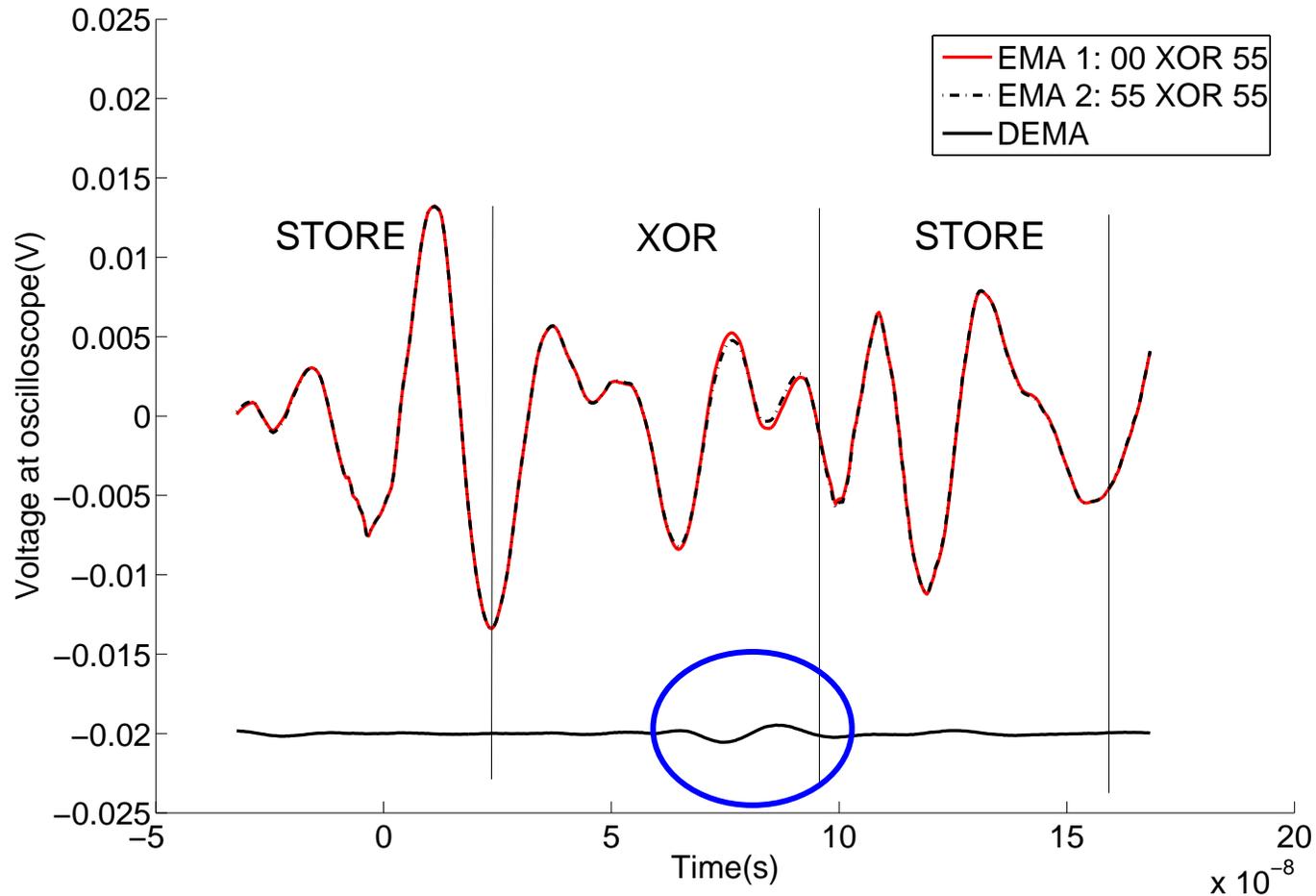
Simulation results

- synchronous XAP processor
- inductive sensor



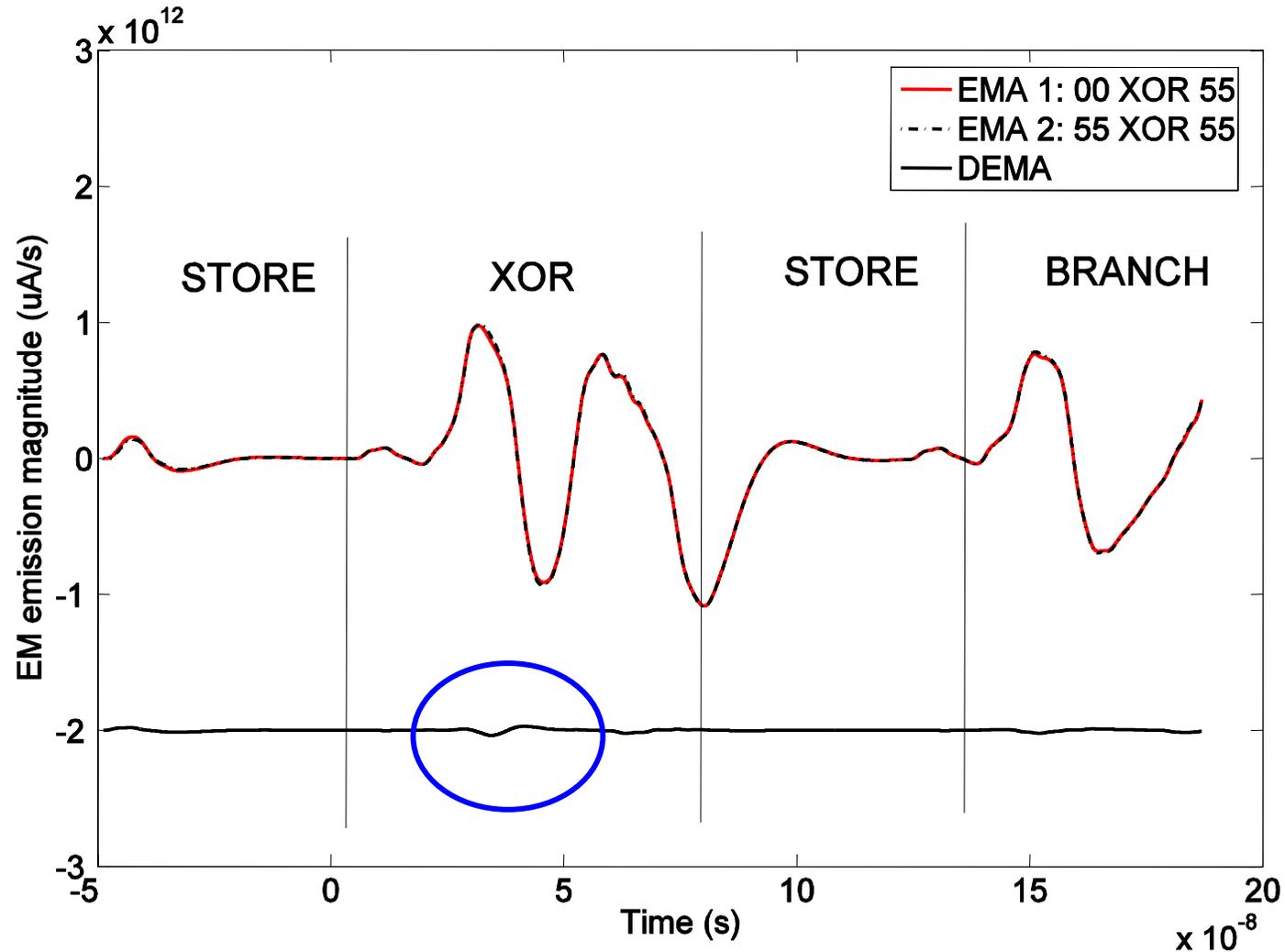
EM measurement results

- synchronous XAP processor
- inductive sensor



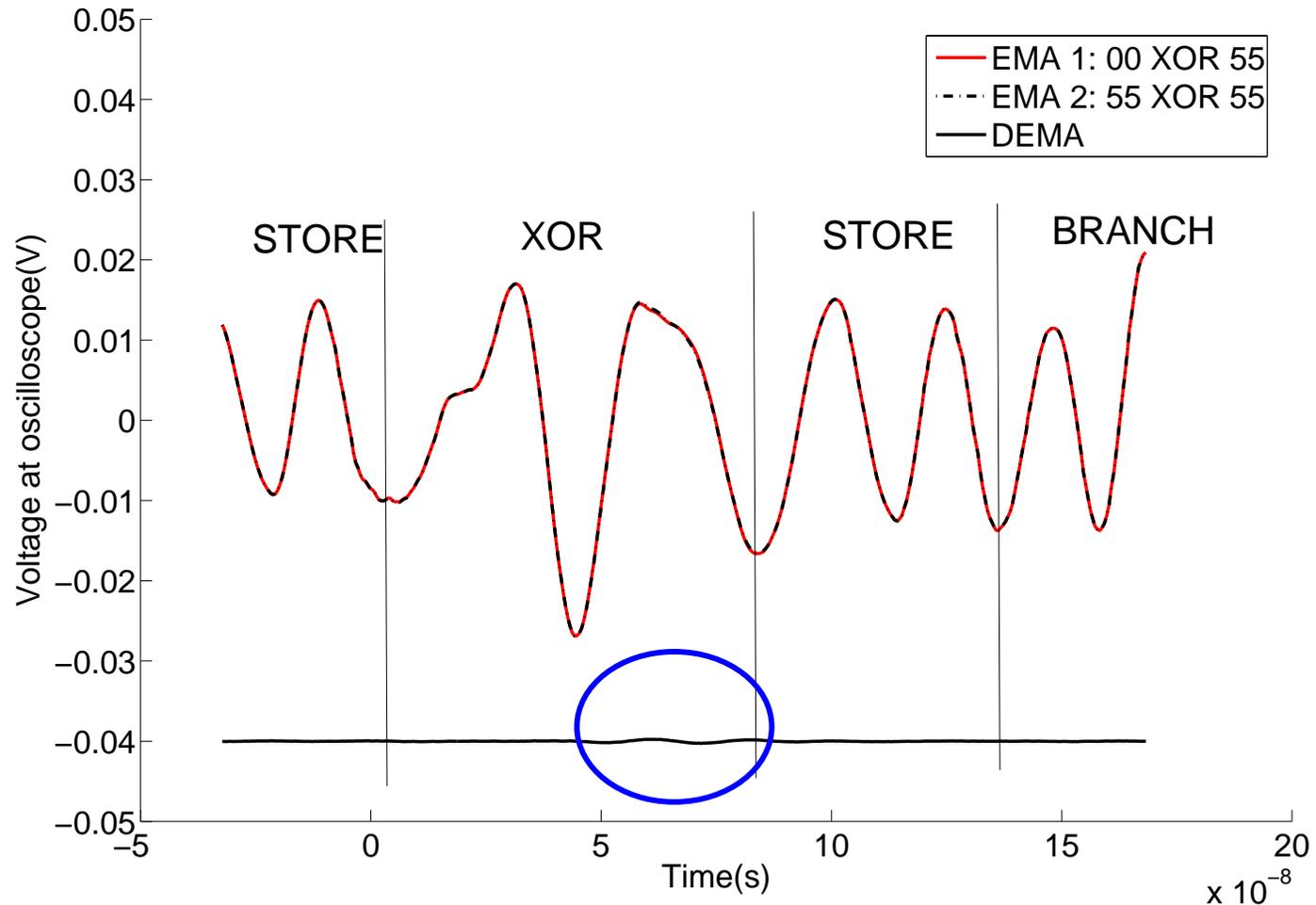
Simulation results

- dual-rail asynchronous XAP processor
- inductive sensor



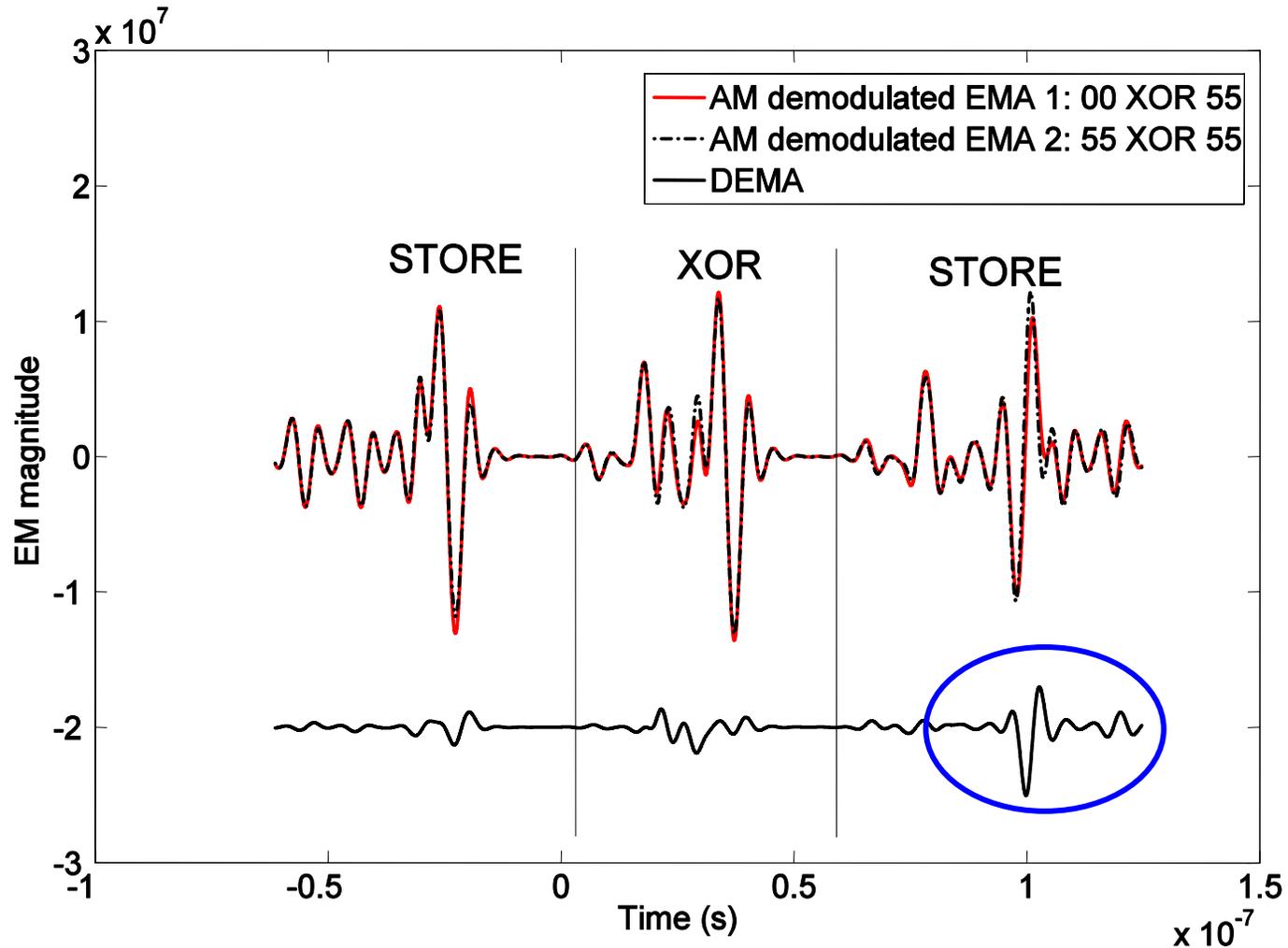
EM measurement results

- dual-rail asynchronous XAP processor
- inductive sensor

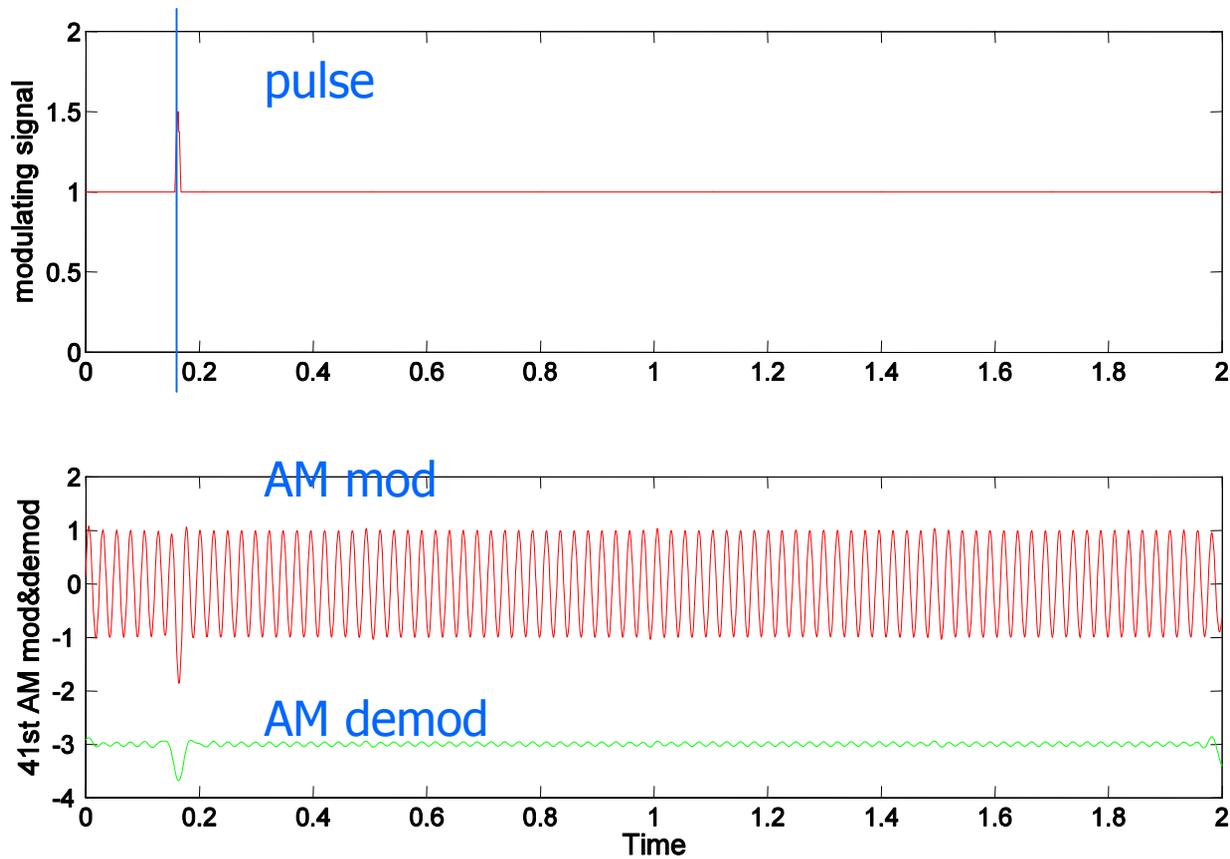


Simulation results

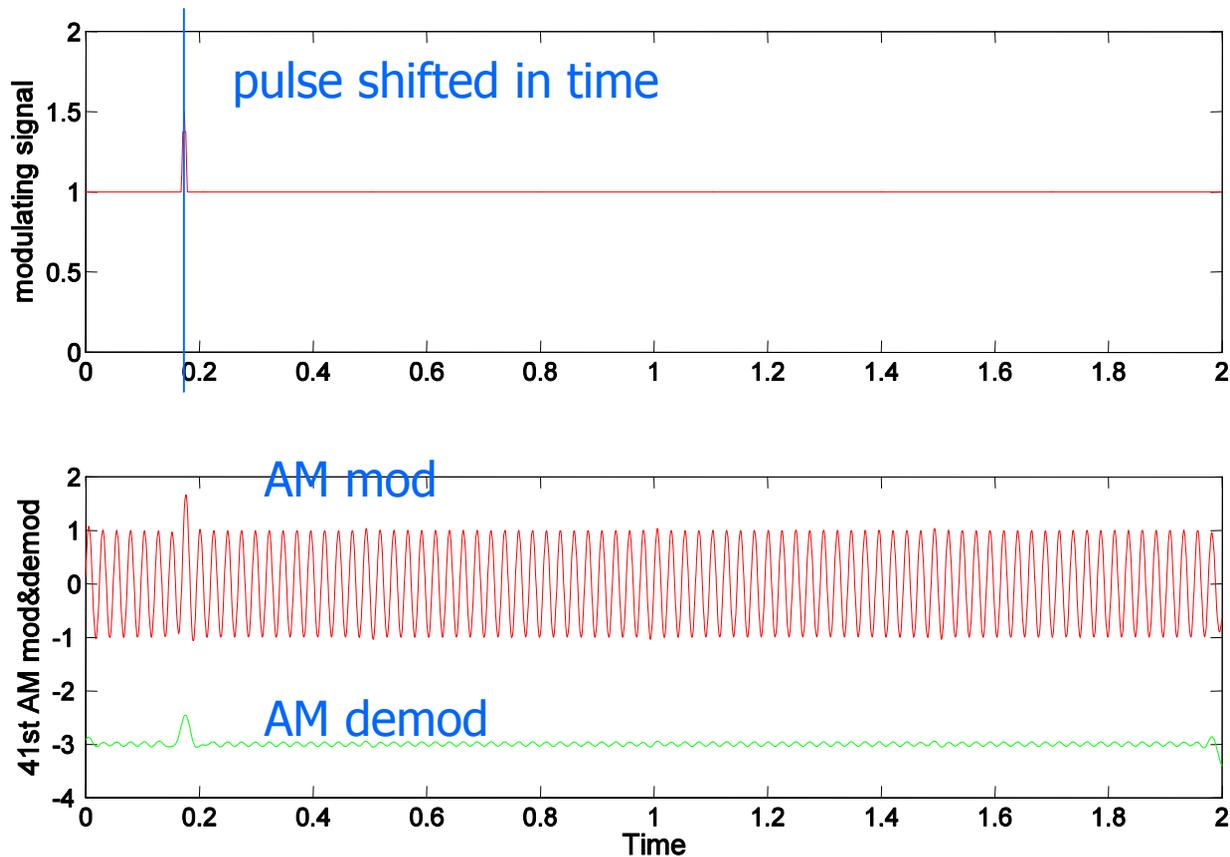
- dual-rail asynchronous XAP processor
- inductive sensor – **modulated** emission

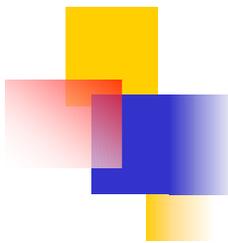


How time shift affects AM modulation and demodulation



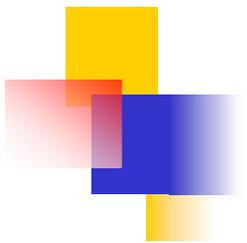
How time shift affects AM modulation and demodulation





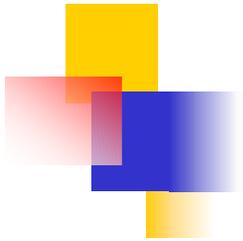
Conclusion

- A simulation methodology for EMA has been proposed
 - EM simulator for modelling Package and PCB
 - Circuit simulator for simulating EMA of chip+package +PCB
 - Data processing for EM analysis according to
 - sensor types (ouput $\propto di/dt$ or $\propto i$)
 - EM emission types (direct or modulated)



Conclusion cont.

- The results also indicates that
 - The synchronous processor under test has data dependent EM emissions
 - The asynchronous processor under test has less data dependent EM emissions in **direct** EMA test, but demonstrated more data dependent EM emissions in **modulated** EMA test



Thank You!